

Docket No. 201225US0/2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Minoru TAKAYA, et al.

SERIAL NO: 09/748,261

GAU: 1714

FILED: December 27, 2000

EXAMINER:

FOR: COMPOSITION DIELECTRIC MATERIAL, COMPOSITE DIELECTRIC SUBSTRATE, PREPREG, COATED METAL FOIL, MOLDED SHEET, COMPOSITE MAGNETIC SUBSTRATE, SUBSTRATE, DOUBLE SIDE METAL FOIL-CLAD SUBSTRATE, FLAME RETARDANT SUBSTRATE, POLYVINYL BENZYL ETHER RESIN COMPOSITION, THERMOSETTING POLYVINYL BENZYL ETHER RESIN COMPOSITION, AND METHOD FOR PREPARING THERMOSETTING POLYVINYL BENZYL ETHER RESIN COMPOSITION

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☐ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☒ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

  
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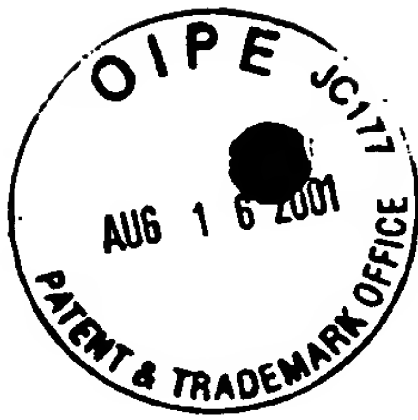
William E. Beaumont

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22850

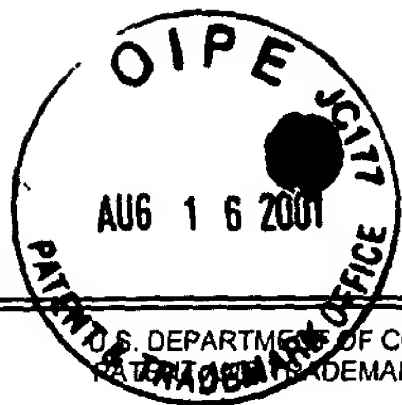
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**LIST OF RELATED CASES**

<u>Docket Number</u>	<u>Serial or Patent No.</u>	<u>Filing or Issue Date</u>	<u>Status or Patentee</u>
0083-0870-0X	09/140,533	08/26/98	PENDING
201225US0*	09/748,261	12/27/00	PENDING

\*Present application; listed for information.



SHEET 1 OF 1

Form PTO 1449  
(Modified)U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

ATTY DOCKET NO.

201225US0

SERIAL NO.

09/748,261

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT

Minoru TAKAYA, et al.

FILING DATE

December 27, 2000

GROUP

1714

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES	NO
	AJ	3-190912	08/20/91	JAPAN (with English Abstract)		X
	AK	0 258 695	03/09/88	EUROPE		
	AL	WO 91/05002	04/18/91	WIPO		
	AM	WO 92/11580	07/09/92	WIPO		
	AN	0 953 608	11/03/99	EUROPE		
	AO	0 878 984	11/18/98	EUROPE		
	AP	2-120040	05/08/90	JAPAN (with English Abstract)		X
	AQ	WO 88/07562	10/06/88	WIPO		
	AR	0 260 443	03/23/88	EUROPE		
	AS					
	AT					
	AU					
	AV					

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AW	
	AX	
	AY	
	AZ	

Examiner

Date Considered

\*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.